

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	2	5866807.pn.	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 14:57	
2	BRS	L2	9	liu near chang.in. and probe\$1	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 14:58	
3	BRS	L3	5	zhang near ming.in. and probe\$1	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 14:59	
4	BRS	L4	2	bullen near david.in. and probe\$1	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 14:59	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
5	BRS	L5	592	73/81.ccls.	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5.15:00	
6	BRS	L6	85	5 and probe\$1	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5.15:01	
7	BRS	L7	4	5 and (array near3 probe\$1)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 15:08	
8	BRS	L8	11822	array near3 probe\$1	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 15:08	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
9	BRS	L9	43	(array near3 probe\$1) near15 (actuator\$1)	USPAT; US-P GPUB; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:23	
10	BRS	L10	362	(spm) near25 (afm)	USPAT; US-P GPUB; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 15:49	
11	BRS	L11	27	(spm) near25 (afm) near15 (wafer or substrate)	USPAT; US-P GPUB; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 15:49	
12	BRS	L12	0	(patterning near compound) near10 (biological)	USPAT; US-P GPUB; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:23	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
13	BRS	L13	40635	(compound) near10 (biological)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:24	
14	BRS	L15	0	(compound) near10 (biological) near15 (substrate or wafer) near15 (tip)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:24	
15	BRS	L16	1	(compound) near10 (biological) near15 (substrate or wafer) near15 (integrated)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:25	
16	BRS	L14	481	(compound) near10 (biological) near15 (substrate or wafer)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:41	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
17	BRS	L17	1	(compound) near10 (biological) near15 (substrate or wafer) near5 (gold)	USPAT; US-P GPUB; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:26	
18	BRS	L18	34	(patterning near compound) with (substrate)	USPAT; US-P GPUB; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:45	
19	BRS	L19	10	(patterning near compound) with (gold)	USPAT; US-P GPUB; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:46	
20	BRS	L20	0	(patterning near compound) with (biological)	USPAT; US-P GPUB; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:58	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
21	BRS	L21	46837	(compound) with (biological)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:46	
22	BRS	L22	21	(compound) with (biological), near10 (gold)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:49	
23	BRS	L23	0	(compound near5 grid) with (biological) near10 (gold)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:49	
24	BRS	L24	3	(compound near5 grid) with (biological)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:50	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
25	BRS	L25	82128	(compound or material) with (biological)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2004/05/05 16:50	
26	BRS	L26	42467	(patterning near compound or material) with (biological)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2004/05/05 16:50	
27	BRS	L27	0	(patterning) near ((compound or material) with (biological))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2004/05/05 16:50	
28	BRS	L28	2441	(patterning) near (compound or material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2004/05/05 16:51	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
29	BRS	L29	0	((patterning) near (compound or material)) near15 (biological)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:51	
30	BRS	L30	519	((patterning) near (compound or material)) near15 (substrate)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:55	
31	BRS	L31	22	((patterning) near (compound or material)) near15 (substrate) near15 (tip or probe)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:56	
32	BRS	L32	0	(plurality near spm) near15 (probe41)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:59	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
33	BRS	L33	2	(plurality near spm) near15 (probe\$1)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 16:59	
34	BRS	L34	2	(plurality near spm) near15 (probe\$1 or tip)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:00	
35	BRS	L35	2	(plurality near spm) near25 (probe\$1 or tip)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:02	
36	BRS	L37	0	(scan\$4 near tube). near15 (probe) near15 (piez)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:01	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
37	BRS	L38	2	(plurality near spm) near25. (probe\$1 or chip)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:02	
38	BRS	L36	145	(scan\$4 near tube) near15 (probe)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:10	
39	BRS	L39	17070 6	(substrate or wafer) near5 (pattern\$3)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:10	
40	BRS	L40	23569	(substrate or wafer) near5 (pattern\$3) near15 (material or compound)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:11	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
41	BRS	L41	214523	(substrate or wafer) near10 (pattern\$3)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:12	
42	BRS	L42	1	(substrate or wafer) near10 (pattern\$3) near15 (interated near circuit)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5.17:13	
43	BRS	L43	1	(substrate or wafer) near10 ((pattern\$3) near5 (interated near circuit))	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:13	
44	BRS	L44	1	(substrate or wafer) near30 ((pattern\$3) near5 (interated near circuit))	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:13	

	Type	L. #	Hits	Search Text	DBs	Time Stamp	Comments
45	BRS	L45	7220	(substrate or wafer) near30 ((pattern\$3) near5 (chip))	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:14	
46	BRS	L46	17357	(substrate or wafer) near30 ((pattern\$3) near5 (device))	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:16	
47	BRS	L47	2265	(substrate or wafer) near30 ((pattern\$3) near5 (die))	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:14	
48	BRS	L48	5	(substrate or wafer) near30 ((pattern\$3) near5 (die)) with compound	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:14	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
49	BRS	L49	138	(substrate or wafer) near30 ((pattern\$3) near5 (device)) with (compound)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:15	
50	BRS	L50	0	(substrate or wafer) near30 ((pattern\$3) near5 (device)) with (compound near10 gold)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:16	
51	BRS	L51	202	(substrate or wafer) near30 ((pattern\$3) near5 (device)) with (compound or gold)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:18	
52	BRS	L52	64	(substrate or wafer) near30 ((pattern\$3) near5 (device)) with (gold)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/05/0 5 17:18	